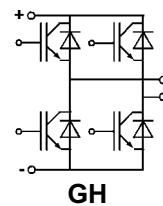
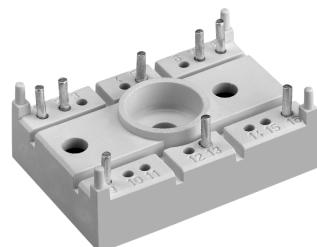


Absolute Maximum Ratings		Values	Units
Symbol	Conditions¹⁾		
V_{CES}		600	V
V_{GES}		± 20	V
I_C	$T_h = 25/80^\circ\text{C}$	30 / 21	A
I_{CM}	$t_p < 1 \text{ ms}; T_h = 25/80^\circ\text{C}$	60 / 42	A
$I_F = -I_C$	$T_h = 25/80^\circ\text{C}$	36 / 24	A
$I_{FM} = -I_{CM}$	$t_p < 1 \text{ ms}; T_h = 25/80^\circ\text{C}$	72 / 48	A
T_j		-40 ... +150	$^\circ\text{C}$
T_{stg}		-40 ... +125	$^\circ\text{C}$
T_{sol}	Terminals, 10 s	260	$^\circ\text{C}$
V_{isol}	AC, 1 min	2500	V

SEMITOP® 2 IGBT Module

SK 25 GH 063



Characteristics		min.	typ.	max.	Units
Symbol	Conditions¹⁾				
V_{CEsat}	$I_C = 25 \text{ A}; T_j = 25 (125)^\circ\text{C}$	-	1,9(2,1)	2,6(2,9)	V
$t_{d(on)}$	$V_{CC} = 300 \text{ V}; V_{GE} = \pm 15 \text{ V}$	-	37	-	ns
t_r	$I_C = 25 \text{ A}, T_j = 125^\circ\text{C}$	-	40	-	ns
$t_{d(off)}$	$R_{Gon} = R_{Goff} = 33 \Omega$	-	200	-	ns
t_f	inductive load	-	30	-	ns
$E_{on} + E_{off}$		-	1,9	-	mJ
C_{ies}	$V_{CE} = 25 \text{ V}; V_{GE} = 0 \text{ V}, 1 \text{ MHz}$	-	1,6	-	nF
$R_{thjh}^{(3)}$	per IGBT	-	-	1,4	K/W
Inverse Diode ²⁾					
$V_F = V_{EC}$	$I_F = 25 \text{ A}; T_j = 25 (125)^\circ\text{C}$	-	1,45(1,4)	1,7(1,75)	V
V_{TO}	$T_j = 125^\circ\text{C}$	-	0,85	0,9	V
r_T	$T_j = 125^\circ\text{C}$	-	22	32	$\text{m}\Omega$
I_{RRM}	$I_F = 25 \text{ A}; V_R = 300 \text{ V}$	-	16	-	A
Q_{rr}	$dI_F/dt = -500 \text{ A}/\mu\text{s}$	-	2	-	μC
E_{off}	$V_{GE} = 0 \text{ V}; T_j = 125^\circ\text{C}$	-	0,25	-	mJ
$R_{thjh}^{(3)}$	per Diode	-	-	1,7	K/W
Mechanical Data					
M1	mounting torque	-	-	2,0	Nm
w		-	21	-	g
Case		T 5			

Features

- Compact design
- One screw mounting
- Heat transfer and isolation through direct copper bonded aluminium oxide ceramic (DCB)
- N channel, homogeneous silicon structure (NPT Non punch-through IGBT)
- High short circuit capability
- Low tail current with low temperature dependence
- UL recognized, file no. E 63 532

Typical Applications

- Switching (not for linear use)
- Inverter
- Switched mode power supplies
- UPS

¹⁾ $T_h = 25^\circ\text{C}$, unless otherwise specified

²⁾ CAL = Controlled Axial Lifetime Technology (soft and fast recovery)

³⁾ Thermal resistance junction to heatsink

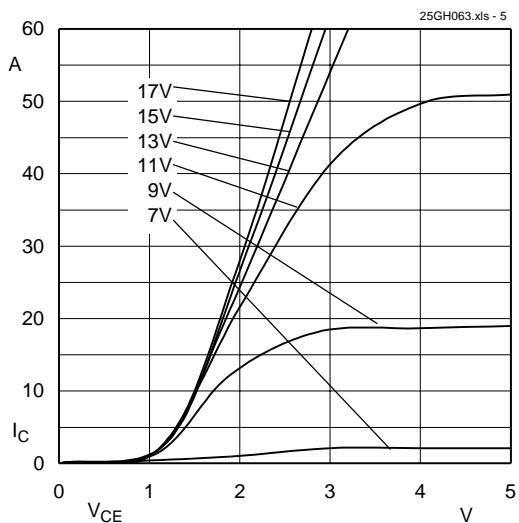


Fig. 5 Typ. output characteristic, $t_p = 80 \mu\text{s}$; 25°C

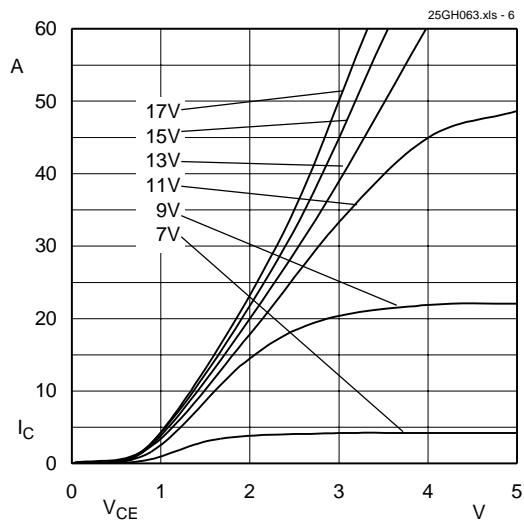


Fig. 6 Typ. output characteristic, $t_p = 80 \mu\text{s}$; 125°C

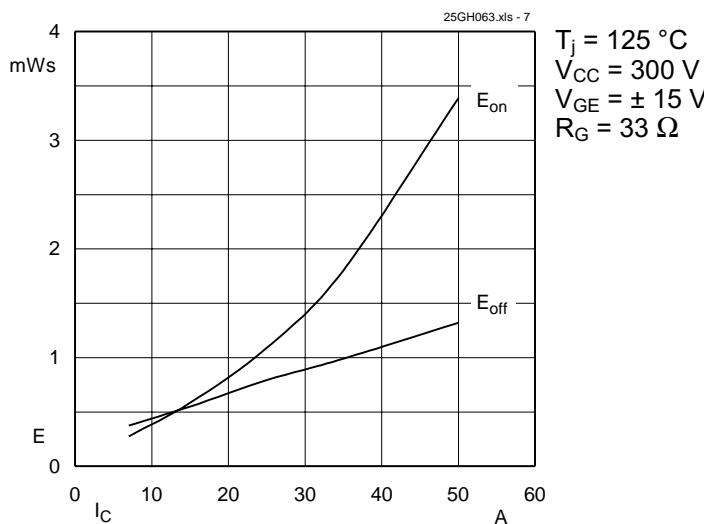


Fig. 7 Turn-on /-off energy = f (I_C)

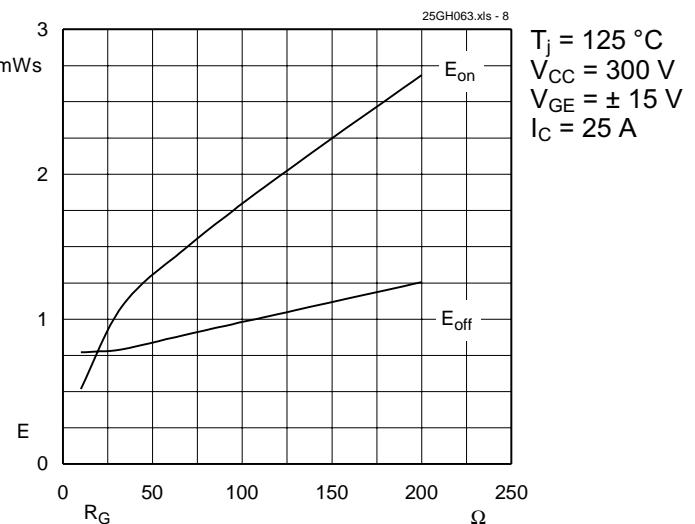


Fig. 8 Turn-on /-off energy = f (R_G)

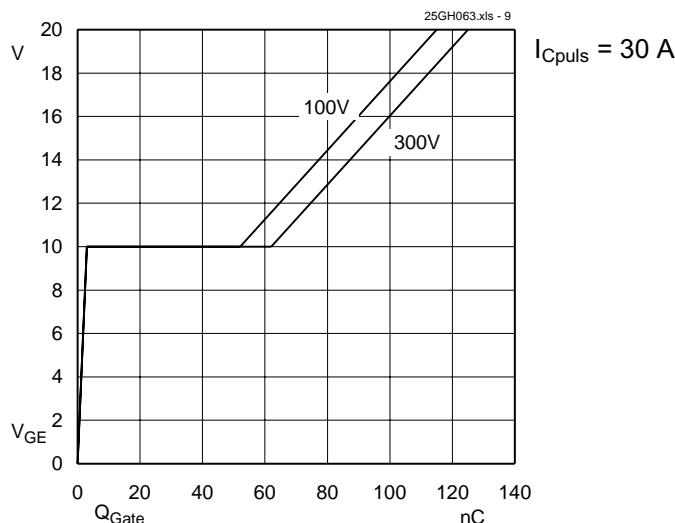


Fig. 9 Typ. gate charge characteristic

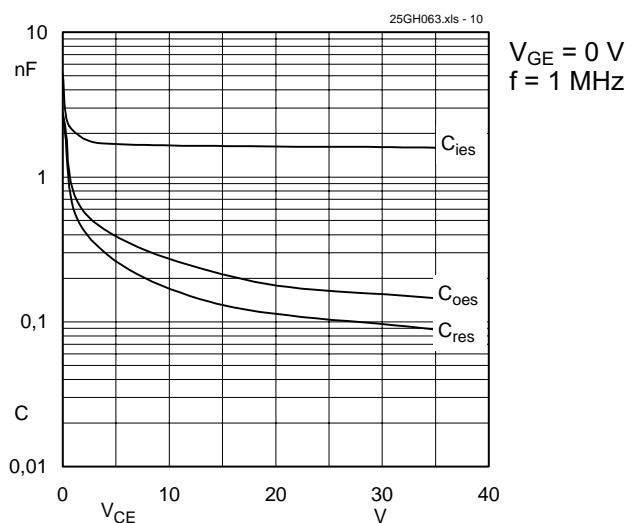


Fig. 10 Typ. capacitances vs. V_{CE}

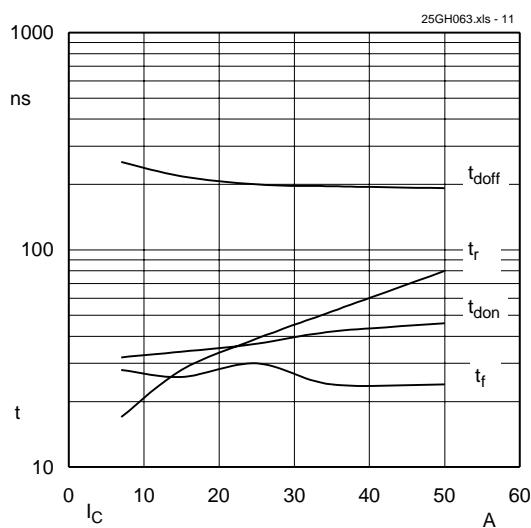


Fig. 11 Typ. switching times vs. I_C

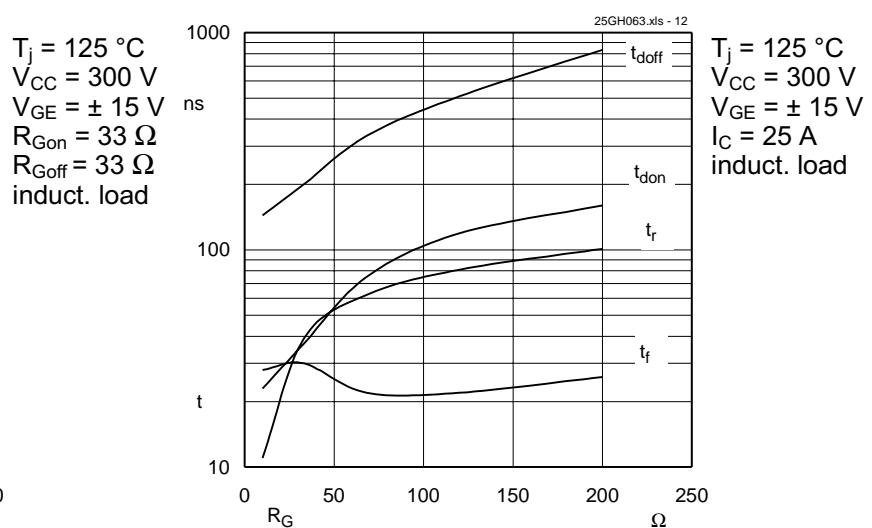


Fig. 12 Typ. switching times vs. gate resistor R_G

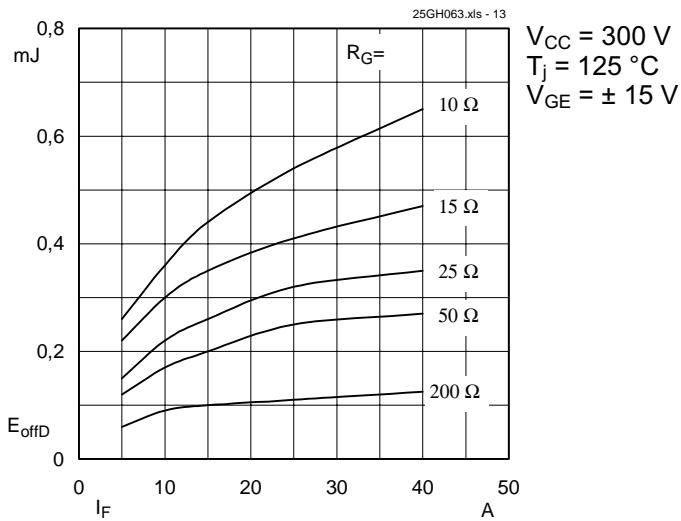
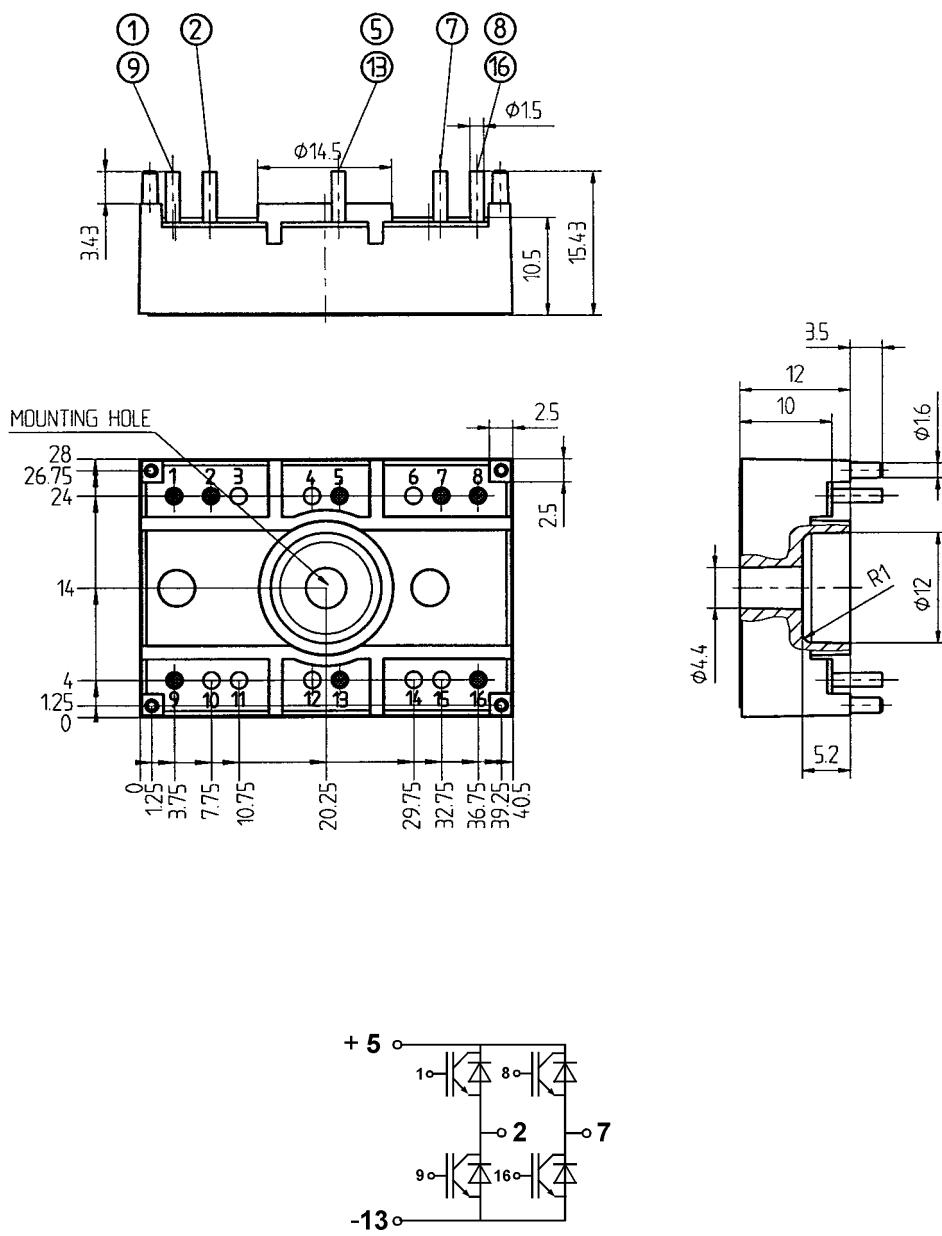


Fig. 13 Diode turn-off energy dissipation per pulse

SEMITOP® 2
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Case T 5



Dimensions in mm

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.